

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

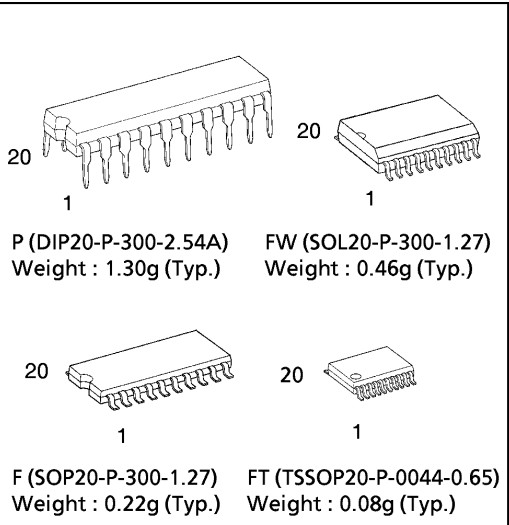
TC74AC540P, TC74AC540F, TC74AC540FW, TC74AC540FT
TC74AC541P, TC74AC541F, TC74AC541FW, TC74AC541FT

OCTAL BUS BUFFER
TC74AC540P/F/FW/FT INVERTING, 3 – STATE OUTPUTS
TC74AC541P/F/FW/FT NON – INVERTING, 3 – STATE OUTPUTS

(Note) The JEDEC SOP (FW) is not available in Japan.

The TC74AC540/TC74AC541 are advanced high speed CMOS OCTAL BUS BUFFERS fabricated with silicon gate and double-layer metal wiring C²MOS technology. They achieve the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation. The TC74AC540 is an inverting type, and the TC74AC541 is a non-inverting type. When either $\overline{G}1$ or $\overline{G}2$ are high, the terminal outputs are in the high-impedance state. All inputs are equipped with protection circuits against static discharge or transient excess voltage.

- FEATURES :
- High Speed..... $t_{pd} = 4.0ns(typ.)$ at $V_{CC} = 5V$
 - Low Power Dissipation..... $I_{CC} = 8\mu A(Max.)$ at $T_a = 25^{\circ}C$
 - High Noise Immunity..... $V_{NIH} = V_{NIL} = 28\% V_{CC} (Min.)$
 - Symmetrical Output Impedance... $|I_{OH}| = I_{OL} = 24mA(Min.)$
Capability of driving 50Ω transmission lines.
 - Balanced Propagation Delays..... $t_{pLH} \approx t_{pHL}$
 - Wide Operating Voltage Range.... $V_{CC} (opr) = 2V \sim 5.5V$
 - Pin and Function Compatible with 74F540/541

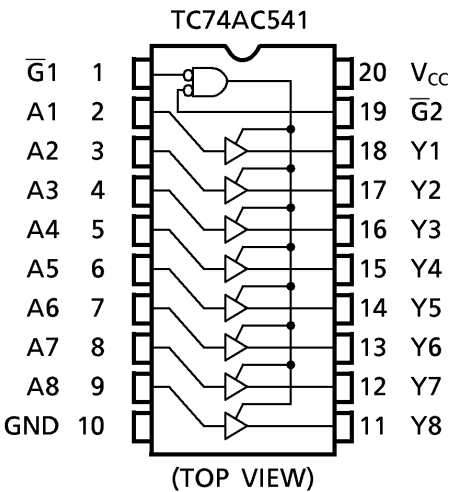
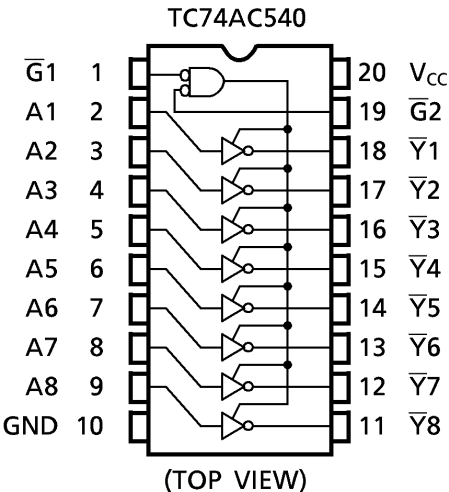


TRUTH TABLE

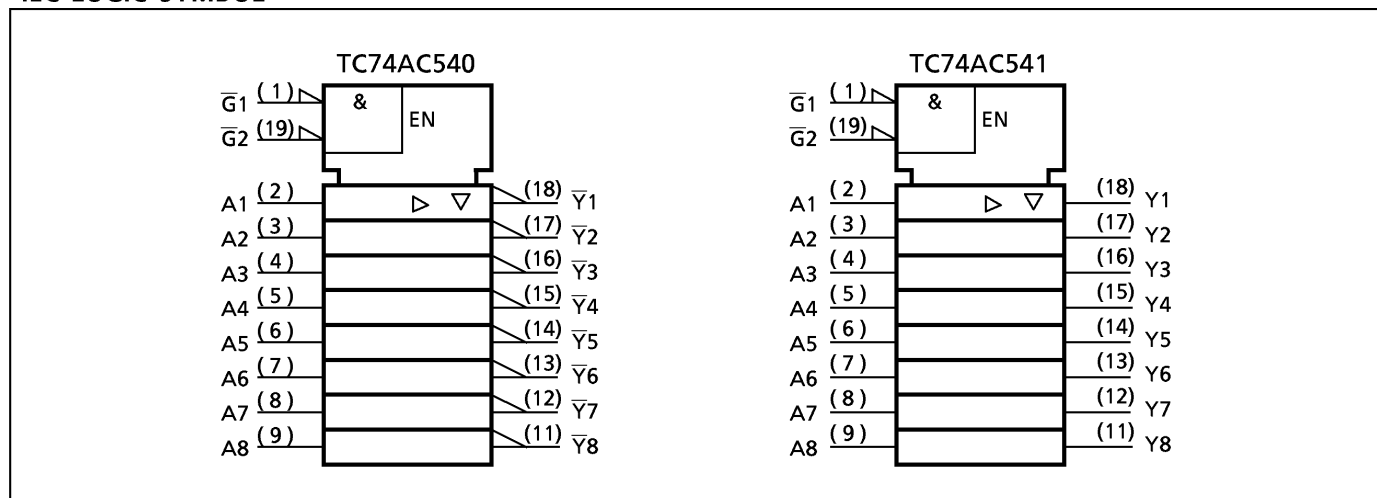
INPUTS			OUTPUTS	
$\overline{G}1$	$\overline{G}2$	A_n	$Y_n *$	$\overline{Y}_n *$
H	X	X	Z	Z
X	H	X	Z	Z
L	L	H	H	L
L	L	L	L	H

X : Don't Care
Z : High Impedance
* : Y_n AC541
 $\overline{Y}_n$ AC540

PIN ASSIGNMENT



IEC LOGIC SYMBOL



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	$-0.5 \sim 7.0$	V
DC Input Voltage	V_{IN}	$-0.5 \sim V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	$-0.5 \sim V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 50	mA
DC Output Current	I_{OUT}	± 50	mA
DC V_{CC} /Ground Current	I_{CC}	± 200	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP/TSSOP)	mW
Storage Temperature	T_{stg}	$-65 \sim 150$	$^{\circ}\text{C}$

*500mW in the range of $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$. From $T_a = 65^{\circ}\text{C}$ to 85°C a derating factor of $-10\text{mW}/^{\circ}\text{C}$ should be applied up to 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	$2.0 \sim 5.5$	V
Input Voltage	V_{IN}	$0 \sim V_{CC}$	V
Output Voltage	V_{OUT}	$0 \sim V_{CC}$	V
Operating Temperature	T_{opr}	$-40 \sim 85$	$^{\circ}\text{C}$
Input Rise and Fall Time	dt/dV	$0 \sim 100$ ($V_{CC} = 3.3 \pm 0.3\text{V}$) $0 \sim 20$ ($V_{CC} = 5 \pm 0.5\text{V}$)	ns / V

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V _{IH}		2.0 3.0 5.5	1.50 2.10 3.85	— — —	— — —	1.50 2.10 3.85	— — —	V
Low - Level Input Voltage	V _{IL}		2.0 3.0 5.5	— — —	— — —	0.50 0.90 1.65	— — —	0.50 0.90 1.65	V
High - Level Output Voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -50μA I _{OH} = -4mA I _{OH} = -24mA I _{OH} = -75mA*	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5	— — —	1.9 2.9 4.4	V
				3.0 4.5 5.5	2.58 3.94 —	— — —	— — —	2.48 3.80 3.85	
				— — —	— — —	— — —	— — —	— — —	
Low - Level Output Voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 50μA I _{OL} = 12mA I _{OL} = 24mA I _{OL} = 75mA*	2.0 3.0 4.5 5.5	— — — —	0.0 0.0 0.0 —	0.1 0.1 0.1 —	— — — —	V
				— — — —	— — — —	— — — —	— — — —	0.1 0.1 0.44 1.65	
				— — — —	— — — —	— — — —	— — — —	— — — —	
3 - State Output Off - State Current	I _{OZ}	V _{IN} = V _{IH} or V _{IL} V _{OUT} = V _{CC} or GND	5.5	—	—	± 0.5	—	± 5.0	μA
Input Leakage Current	I _{IN}	V _{IN} = V _{CC} or GND	5.5	—	—	± 0.1	—	± 1.0	
Quiescent Supply Current	I _{CC}	V _{IN} = V _{CC} or GND	5.5	—	—	8.0	—	80.0	

* : This spec indicates the capability of driving 50Ω transmission lines.

One output should be tested at a time for a 10ms maximum duration.

AC ELECTRICAL CHARACTERISTICS (C_L = 50pF, R_L = 500Ω, Input t_r = t_f = 3ns)

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
Propagation Delay Time*	t _{pLH} t _{pHL}		3.3 ± 0.3 5.0 ± 0.5	— —	6.8 4.7	10.5 7.0	1.0 1.0	12.0 8.0	ns
			3.3 ± 0.3 5.0 ± 0.5	— —	6.8 4.7	11.4 7.5	1.0 1.0	13.0 8.5	
Output Enable Time	t _{pZL} t _{pZH}		3.3 ± 0.3 5.0 ± 0.5	— —	9.6 6.4	15.8 10.0	1.0 1.0	18.0 11.4	
			3.3 ± 0.3 5.0 ± 0.5	— —	7.7 6.4	12.3 9.2	1.0 1.0	14.0 10.5	
Output Disable Time	t _{pLZ} t _{pHZ}		3.3 ± 0.3 5.0 ± 0.5	— —	7.7 6.4	12.3 9.2	1.0 1.0	14.0 10.5	
Input Capacitance	C _{IN}			—	5	10	—	10	pF
Output Capacitance	C _{OUT}			—	10	—	—	—	
Power Dissipation Capacitance	C _{PD} (1)	TC74AC540		—	25	—	—	—	
		TC74AC541		—	28	—	—	—	

Note(1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

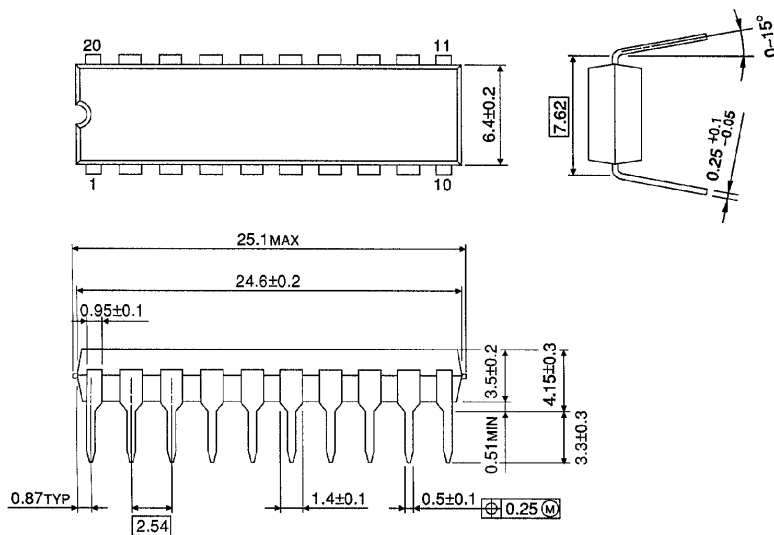
$$I_{CC}(\text{opr.}) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC} / 8 \text{ (per bit)}$$

(2) * for TC74AC540 only

** for TC74AC541 only

DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)

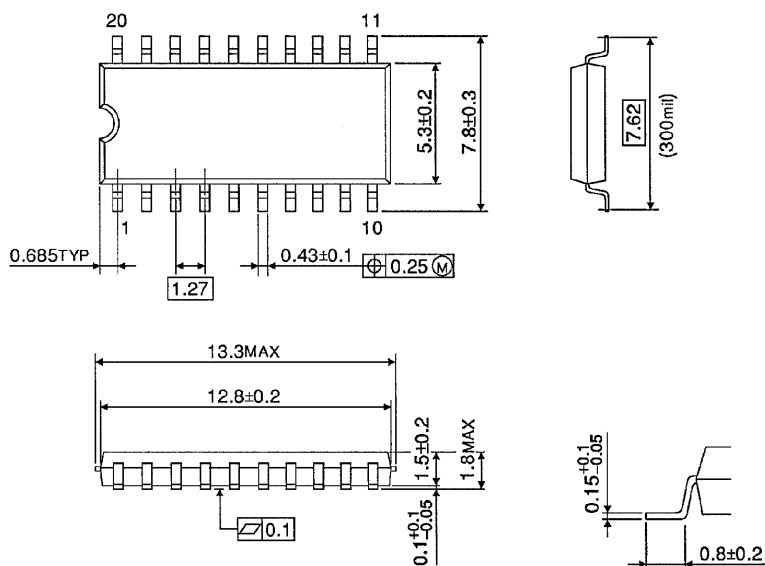
Unit in mm



Weight : 1.30g (Typ.)

SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)

Unit in mm

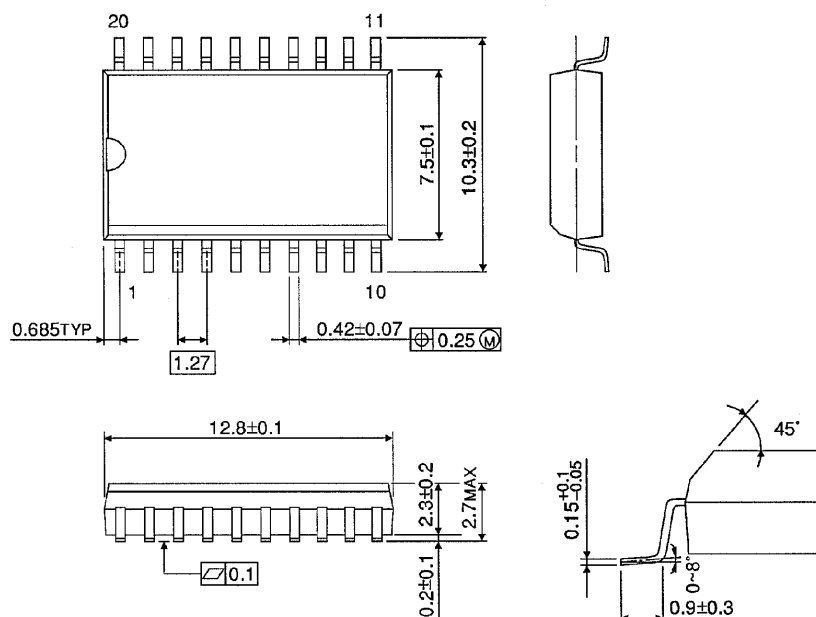


Weight : 0.22g (Typ.)

SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)

Unit in mm

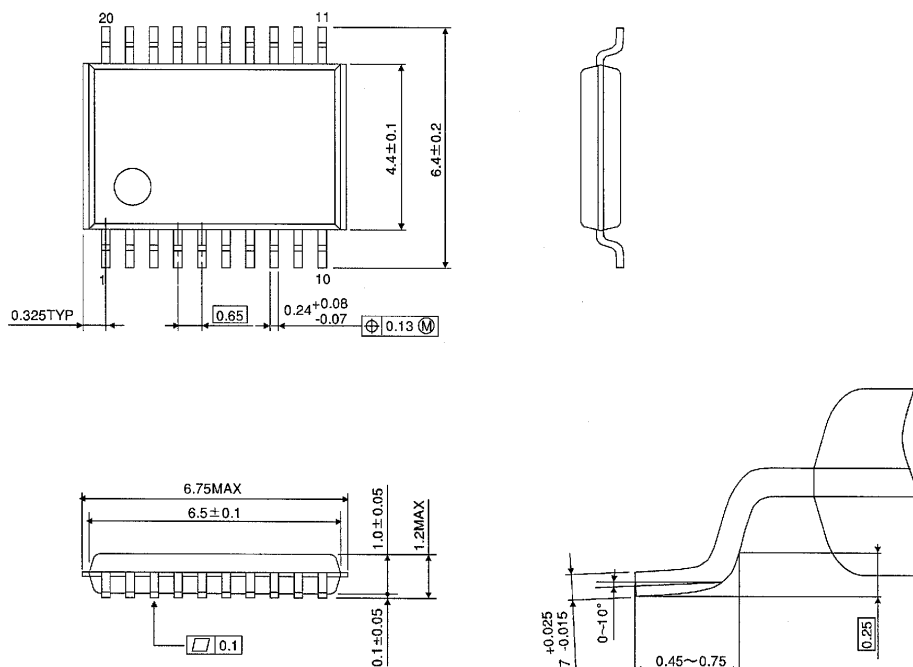
(Note) This package is not available in Japan.



Weight : 0.46g (Typ.)

TSSOP 20PIN PACKAGE DIMENSIONS (TSSOP20-P-0044-0.65)

Unit in mm



Weight : 0.08g (Typ.)

RESTRICTIONS ON PRODUCT USE

000707EBA

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